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Part Number:

73943-4000

Status:

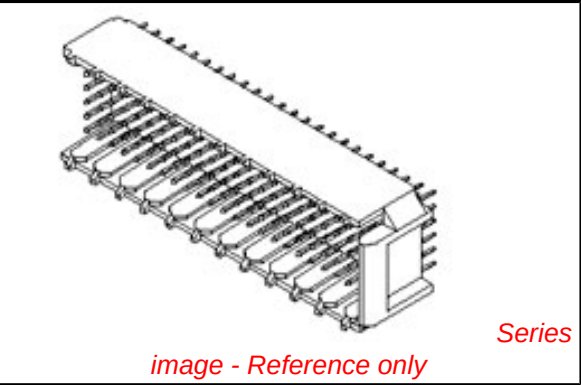
Active

Overview:

HDM® Backplane Connector System

Description:

HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Closed End, 72 Circuits



Documents:

3D Model

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

73943

Application

Backplane

Comments

Solder Tail

Component Type

PCB Header

Overview

HDM® Backplane Connector System

Product Name

HDM®

Style

N/A

UPC

800753945159

Physical

Circuits (Loaded)

72

Circuits (maximum)

72

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

No

Keying to Mating Part

None

Material - Metal

Phosphor Bronze

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Net Weight

3.554/g

Number of Columns

12

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length

3.00mm

PCB Locator

No

PCB Retention

None

PCB Thickness - Recommended

2.50mm

Packaging Type

Tube

Pitch - Mating Interface

2.00mm

Pitch - Termination Interface

2.00mm

Plating min - Mating

0.762µm

Plating min - Termination

2.540µm

Stackable

Yes

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-55°C to +105°C

Termination Interface: Style

Through Hole

EU RoHS

ELV and RoHS Compliant

REACH SVHC

Contains SVHC: No

Low-Halogen Status

Low-Halogen

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
73943Series

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | [FAQ](#)
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global	
Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Sales Drawing	SD-73943-001
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